

ADHESIVE FILM FOR GRINDING BACK FACE OF WAFER

ABSTRACT

The present disclosure provides an adhesive film for grinding a back face of a wafer including a multilayer base including an upper base layer and a lower base layer, a first adhesive layer disposed on a top face of the upper base layer, and a second adhesive layer disposed between the upper base layer and the lower base layer, wherein the second adhesive layer is made of an adhesive composition containing a light-transmissive adhesive resin and light-scattering particles, wherein the second adhesive layer satisfies a following [Relationship 1], and wherein the light-scattering particles have a refractive index in a range of 1.42 to 1.60, thereby reducing or suppressing an occurrence of an adhesive residue in the wafer back grinding process, and improving thickness uniformity of the wafer after the back face grinding process while having an excellent buffering effect on a surface of the wafer.

$$[\text{Relationship 1}]: 0.05 \leq |A-B| \leq 0.2$$

in the [Relationship 1], A is a refractive index of the light-transmissive adhesive resin, and B is the refractive index of the light-scattering particles.

<FIG. 2>